

# TI *Live!* INDIA AUTOMOTIVE SEMINAR

## JÜRGEN AUSTEN

BLUETOOTH® LOW ENERGY CONNECTIVITY  
SOLUTIONS FOR AUTOMOTIVE APPLICATIONS

# Agenda

- *Bluetooth*® Low Energy in automotive - market trends
- TI Bluetooth LE product overview
  - Hardware
  - Software
- Application use-cases
  - Bluetooth LE cluster for 2W
  - Car access
  - Infotainment
  - TPMS
  - Smart helmet
- Dual-mode Bluetooth

# Agenda

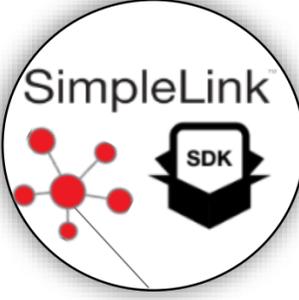
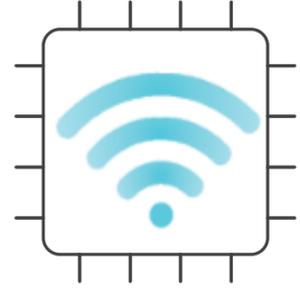
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  - TPMS
  - Smart helmet
- Dual-mode Bluetooth

# TI Connectivity

- ★ Development activity
- ★ Regional support center



# TI Connectivity | Enabling low power wireless for >20yrs

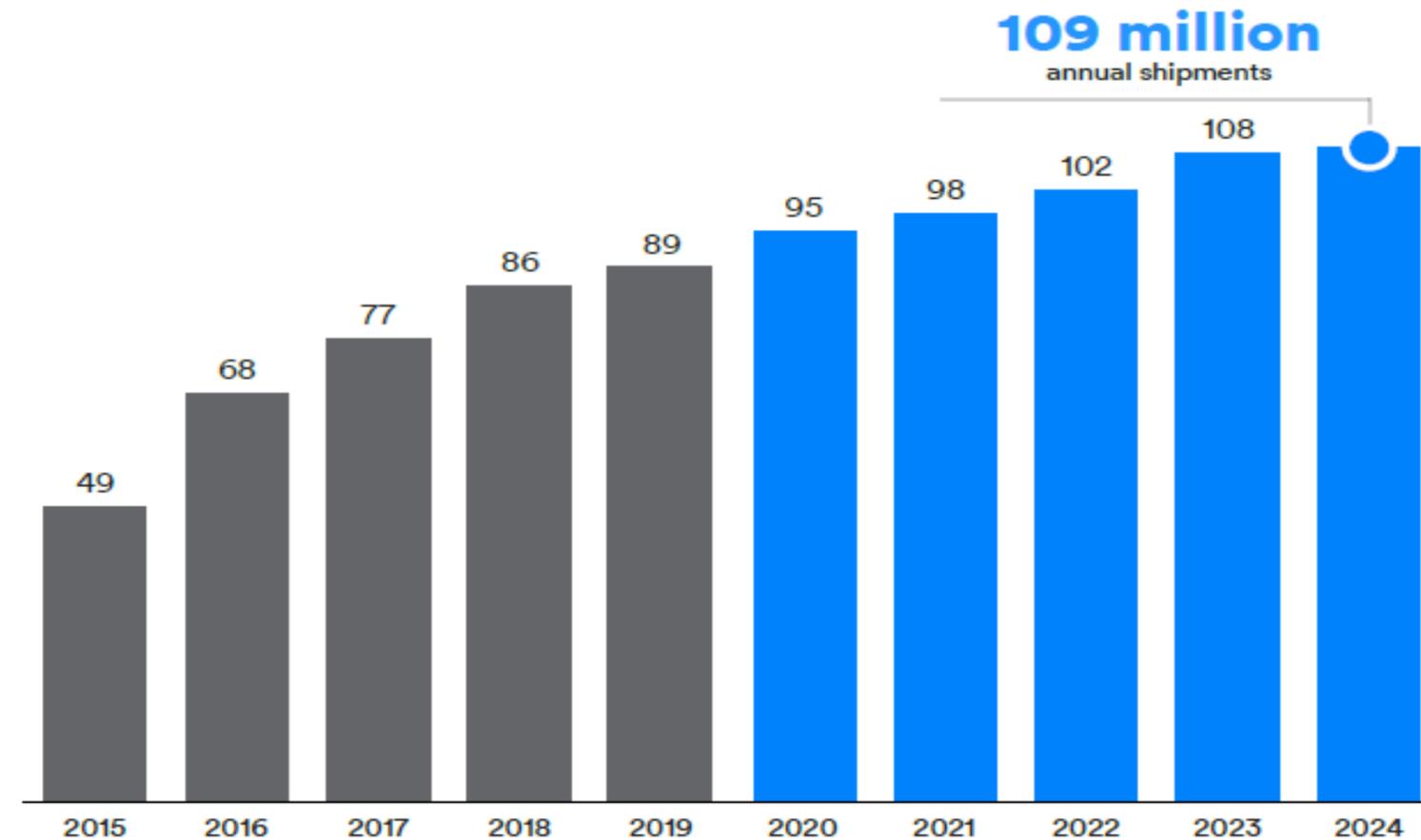
				
<p><b><u>Low power radio for unlicensed bands</u></b></p> <ul style="list-style-type: none"> <li>• Robust radios</li> <li>• Up to 10km range</li> <li>• Up to 100Mbps</li> <li>• Up to 10yrs battery life</li> </ul>	<p><b><u>Driving innovation</u></b></p> <ul style="list-style-type: none"> <li>• BLE 5.x</li> <li>• WiFi IoT</li> <li>• Localization</li> <li>• Crystal free (BAW)</li> <li>• Cable replacement</li> </ul>	<p><b><u>Software Scalability</u></b></p> <ul style="list-style-type: none"> <li>• Quick time to market</li> <li>• Highest flexibility</li> <li>• SW reuse</li> <li>• Easy switching within SimpleLink family</li> </ul>	<p><b><u>Hardware Scalability</u></b></p> <ul style="list-style-type: none"> <li>• From transceivers to wireless MCU and modules</li> <li>• Scalability on RF, computation and memory</li> </ul>	<p><b><u>Complete development environment</u></b></p> <ul style="list-style-type: none"> <li>• Code composer</li> <li>• SysConfig</li> <li>• Smart RF Studio</li> <li>• SL Academy</li> <li>• ...</li> </ul>

# Bluetooth Low Energy | Automotive Market Trends

Bluetooth® technology creates connections between the car and driver that support new levels of safety, security, and access while enhancing the in-car experience. Thanks to lower power consumption, enhanced performance, and improved reliability, Bluetooth technology is the automotive standard for both in and out of the car – including keyless entry systems and in-car infotainment.

## Bluetooth® Automotive Device Shipments

numbers in millions



Source: ABI Research, 2020 [BT SIG: 2020 Market Update-EN.pdf](#)

Transition from BT Classic for mobile phone connection towards BLE  
BLE Bluetooth Low Energy enables new use cases for automotive applications

# Connected Car | TI automotive end equipments

## Car Access (Key fobs)

*Transition from LF and UHF  
towards  
Bluetooth LE based systems*

## Phone as a Key

*Bluetooth LE defined as  
standard for all phone as a  
key systems*



## Wireless BMS

*(Battery Management System)*

*Lowest system cost BMS  
Highest system availability  
Weight savings*

## Infotainment

*Bluetooth LE based  
mobile phone and helmet  
connection*

## TPMS

*Transition from LF and UHF  
towards  
Bluetooth LE based systems*

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# Connectivity | Most Reliable Low Power Wireless 2.4 Portfolio

## Bluetooth LE 5 & Proprietary

Bluetooth LE 5, Mesh, Direction Finding

**CC2652R7**  
704kB, 144kB  
7x7  
Bluetooth and multiprotocol w/ on-chip OTA

M4F

**CC2642R**  
352kB, 80kB  
7x7  
Bluetooth 5.1, Mesh, RTLS

M4F

**CC2640R2F**  
128kB, 20kB  
4x4, 5x5, 7x7, WCSP  
Network attached & low power sensing

M3

**CC2640R2L**  
128kB, 20kB  
5x5, 7x7  
Network attached & non-sensing application

M3

## Bluetooth LE 5 & Proprietary

AUTOMOTIVE

**CC2642R-Q1**  
352kB, 80kB  
7x7  
Bluetooth 5.1, Mesh, RTLS

M4F

**CC2640R2F-Q1**  
128kB, 20kB  
4x4, 5x5, 7x7, WCSP  
Network attached & low power sensing

M3

## 2.4 GHz Multiprotocol

**CC2652R7**  
704kB, 144kB  
7x7  
CHIP, Multiprotocol with on-chip OTA

M4F

**CC2652RB (BAW)**  
352kB, 80kB  
7x7  
Single protocol, system provisioning

M4F

**CC2652R (P)**  
352kB, 80kB  
7x7  
Single protocol, system provisioning

M4F

## Bluetooth LE 5 & Proprietary

System in Package (SIP)

**CC2652RSIP**  
352kB, 80kB  
7x7

M4F

### Platform Highlights

- Lowest 1.0  $\mu$ A standby current consumption
- Integrated PA up to +20dBm (+10dBm coin cell optimized)
- Pin-to-pin QFN compatibility and chip-scale package opts.

### Key Features

- Bluetooth support
- Zigbee support
- Thread support
- Matter support
- Sensor Controller
- +20dBm Integrated PA
- BAW Resonator

NEW

Production

# TI Bluetooth LE portfolio overview

Part number 	Typical use case 	Flash (kB)	RAM (kB)	BLE version	# of connections	BLE Long range	BLE Mesh	2Mbps PHY	Temp range	Low power sensor controller	Low power	Package options (same size = pin to pin)
<b>CC2640R2L</b> Lowest cost basic Bluetooth LE <i>Lowest 1ku price in the market</i>	- Bluetooth LE peripheral / end node - Beacon	128 + 147 (ROM)	28	5.1	4			YES	-40C to 85C		1.5uA Standby 100 nA shutdown +5dBm TX @ 9.1mA	5x5mm QFN (15 GPIO) 7x7mm QFN (31 GPIO)
<b>CC2640R2F</b> Lowest power basic Bluetooth LE for sensor applications Smallest size option	- Bluetooth LE peripheral / end node - Low power sensor - Beacon	128 + 147 (ROM)	28	5.1	4			YES	-40C to 85C	YES	1.1uA Standby 100 nA shutdown +5dBm TX @ 9.1mA	2.7x2.7mm WSCP (14GPIO) 4x4mm QFN (10 GPIO) 5x5mm QFN (15 GPIO) 7x7mm QFN (31 GPIO)
<b>CC2651R/P</b> Bluetooth LE with long range 20dBm TX power option <i>Sampling Now, 4Q RTM</i>	- Bluetooth LE peripheral/central - On chip OTA - Bluetooth Mesh friend node	352 + 40 (ROM)	40	5.2	16	YES	YES	YES	-40C to 105C		0.94uA Standby 150 nA shutdown +5dBm TX @ 9.6mA	5x5mm QFN (15 GPIO) 7x7mm QFN (31 GPIO)
<b>CC2642R/52R/52P/52RB</b> Full features Bluetooth LE for all applications 20dBm TX power option BAW option available (CC2652RB)	- Bluetooth LE peripheral/central - Bluetooth LE Multirole - On chip OTA - Full Bluetooth Mesh - Multiprotocol (BLE, ZB or Thread) - Real time locationing	352 + 256 (ROM)	88	5.2	32	YES	YES	YES	-40C to 105C	YES	0.94uA Standby 150 nA shutdown +5dBm TX @ 9.6mA	7x7mm QFN (31 GPIO)
<b>CC2652R7/P7</b> More Flash memory for advanced features and applications 20dBm TX power option <i>Sampling Now, 4Q RTM</i>	- Bluetooth LE peripheral/central - Bluetooth LE Multirole - On chip OTA - Full Bluetooth Mesh - Multiprotocol (BLE, ZB and Thread) - Real time locationing	704 + 256 (ROM)	152	5.2	32	YES	YES	YES	-40C to 105C	YES	1.2uA Standby 150 nA shutdown +5dBm TX @ 9.6mA	7x7mm QFN (31 GPIO)

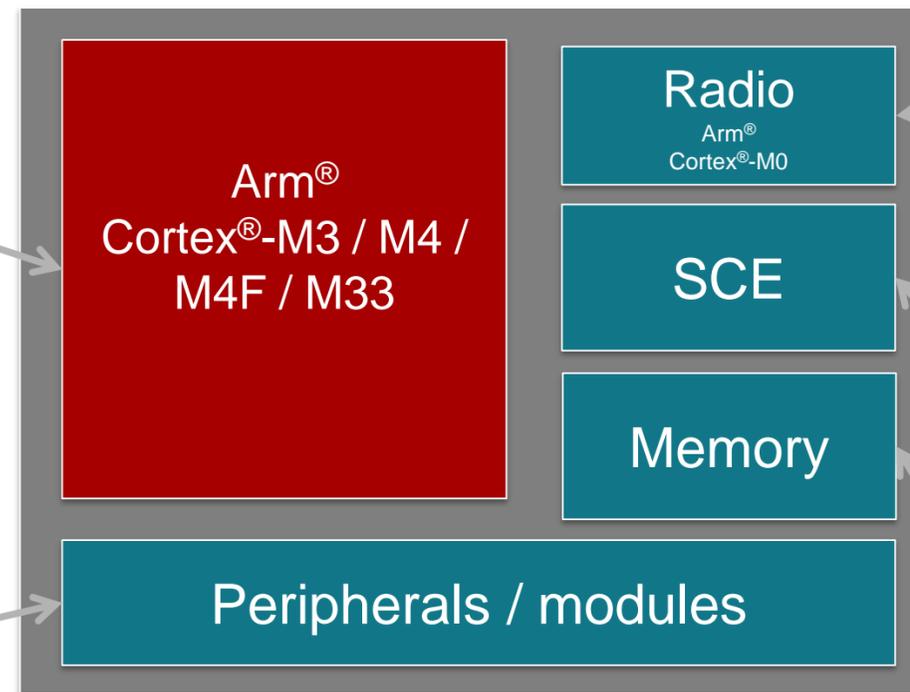
# 2.4 GHz Connectivity | Device architecture

### Application MCU

- Application
- Profiles / services
- TI RTOS
- Peripheral drivers and libraries
- Royalty free protocol stacks

### Peripherals / modules

- DC/DC converter
- Temp/battery monitor
- AES
- GPIO
- Timers
- UART / SPI
- I2C / I2S
- DMA



QFN package: 4x4 mm, 5x5 mm 7x7 mm  
WCSP: 2.7x2.7 mm

### Low power

- **Standby:** <1 uA (RTC and full RAM retention)
- **Shutdown:** 100 nA
- **RX / TX @ 0 dBm:** 5.9 mA / 6.1 mA

### Radio

- Multi-band, multi-protocol
- Software configurable
- Power output:
  - +5 dBm / +20 dBm @ 2.4 GHz
- Strong Sensitivity:
  - 1-Mbps BLE: -97 dBm
  - 802.15.4: -100 dBm
- Industry's first completely crystal-less wireless MCU using **BAW** technology

### Sensor controller engine

- ADC and comparators
- Digital sensor readings
- Capacitive sensing

### Memory

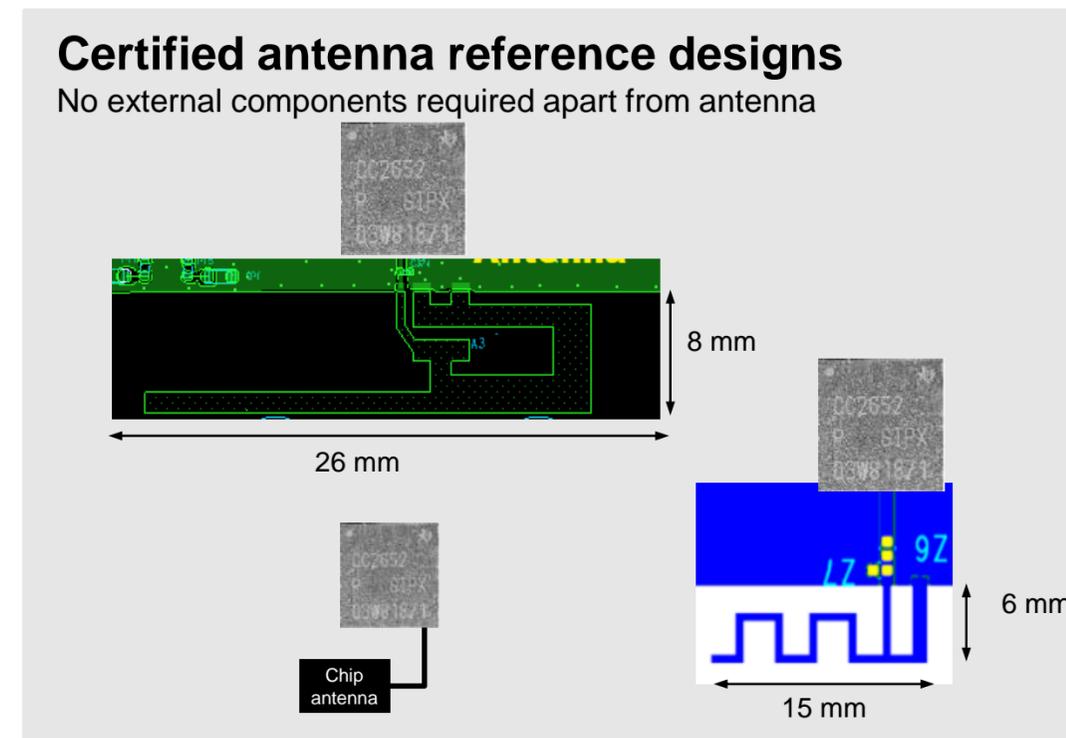
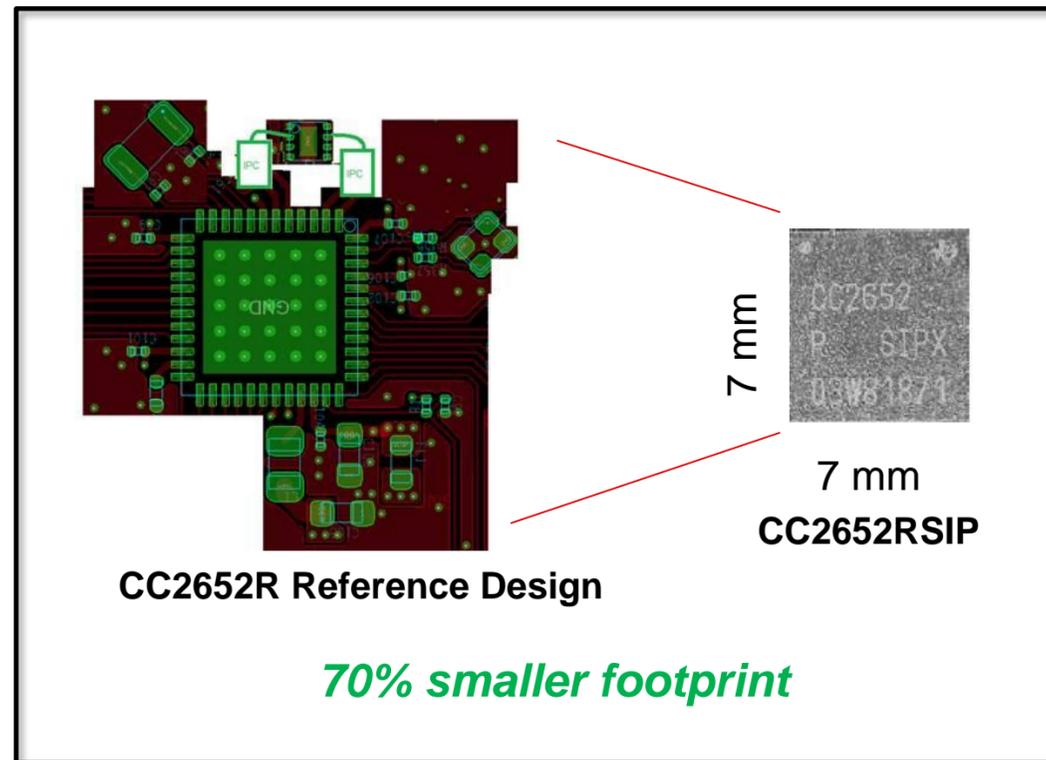
- **Flash:** 128 KB / 352 KB / 704 KB / 1 MB
- **RAM:** 28 KB / 40 KB / 88 KB / 152 KB / 296 KB (+ cache)
- **ROM:** 147 KB / 256 KB

# CC2652RSIP solution

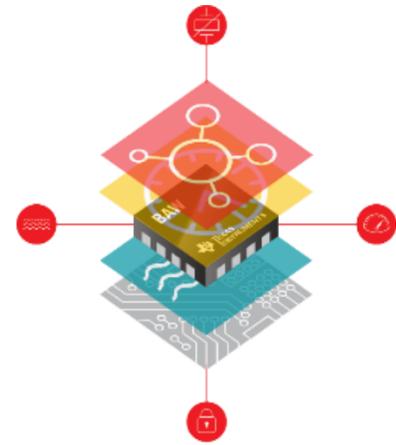
Pre-certified system-in-package wireless MCU to solve space constraint applications

## BENEFITS:

- Reduce overall solution size by 70%
- Enables fast-time to market
- No external components required
  - Integrated passives for all power management
  - Integrated 48 MHz and 32-kHz crystal
  - Integrated antenna matching circuits
- Industry leading 1- $\mu$ A standby current (10+ years battery life on coin cell)
- 352-kB flash and up to 80-kB RAM
- Up to 32 GPIOs
- 105° C temperature range



# CC2652RB | BAW resonation for crystal-less applications



- TI Bulk Acoustic Wave (BAW) resonator
- The industry's only crystal-less wireless MCU solution
- On-chip MEMS resonator that serves as a high-precision, low-jitter clocking reference
- BLE 5.2 qualified, supports Thread and Zigbee with multiprotocol functionality

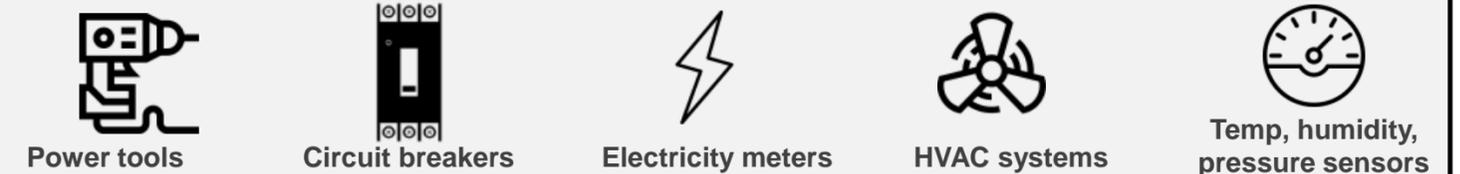


**CC2652RB** wireless MCU:  
BLE 5.2 qualified and support for Zigbee,  
Thread and Multiprotocol

## Why TI?

Lower solution cost	<ul style="list-style-type: none"> <li>• On-chip MEMS resonator that eliminates the need for external high frequency crystal</li> <li>• \$0.05 to \$0.10 lower cost than discrete solution with external crystal</li> </ul>
Smaller, simpler solution	<ul style="list-style-type: none"> <li>• 30% space savings with no high frequency crystal or routing</li> </ul>
More stable solution in harsh environments resulting in fewer MCU timing errors and transmission issues	<ul style="list-style-type: none"> <li>• Less PPM variance when tested against MIL-STD-883H for mechanical shock</li> <li>• Ability to actively compensate BAW resonator for greater stability over temperature variance and battery voltage</li> </ul>
Simplified supply chain	<ul style="list-style-type: none"> <li>• No need to source high frequency crystals</li> </ul>

## Key Applications



## Resources / Getting started

Nick Smith 2018

1. [Get the LaunchPad development kit](#)
2. [Download the SDK](#)
3. [Follow training / documentation](#)



- [Minimizing Frequency Error Due to Soldering Process on CC2652RB Crystal-Less MCU](#)
- [Exploring IoT wireless connectivity in mechanical shock and vibration environments](#)
- [SimpleLink Crystal-Less Wireless MCU based on TI BAW technology](#)
- [Running Bluetooth® Low Energy on CC2640 Without 32 kHz Crystal \(Rev. C\)](#)

[Getting Started With CC2652RB for Crystal-less BAW Operation](#)

# SimpleLink™ | Connectivity Bluetooth® LE Software

## Bluetooth® LE 2Msym/s and Long Range PHY

- Bluetooth 5.1 PHYs for 2Msym/s and Long Range

## Bluetooth® LE + Wi-Fi Coexistence

- 3-wire Co-ex interface (conformance to Broadcom Wi-Fi® standards), 1-wire SimpleLink™ Co-ex interface

## Secure OAD – On-Chip, Off-Chip

- Authenticate an image using ECDSA before installing and executing

## SysConfig GATT Builder

- Simplify creation and configuration of Bluetooth® LE Profiles

# 2.4 GHz | Wi-Fi + Bluetooth LE Coexistence

## What is Coexistence?

Co-located Wi-Fi and *Bluetooth*® Low Energy radios manage their RF activity during 2.4-GHz frequency band access.

1-wire coexistence scheme supported on SimpleLink devices

## Key devices supported:

- CC2642R
- CC2652RX (P)
- CC3230/CC3235
- CC3130/CC3135



## Key Features

Combo 2-Chip design	<ul style="list-style-type: none"> <li>• Wi-Fi + BLE capability for both provisioning &amp; peripheral role</li> </ul>
Low power design for continuous connectivity	<ul style="list-style-type: none"> <li>• Wi-Fi: 0.7uA DTIM 1 beacon receive profile</li> <li>• BLE: lowest power standby 0.94uA</li> </ul>
Security features	<ul style="list-style-type: none"> <li>• Wi-Fi: Personal &amp; Enterprise-WPA3 support</li> <li>• BLE: AES-256, SHA2, ECC/RSA, TRNG</li> </ul>
Ease of certification	<ul style="list-style-type: none"> <li>• Regulatory certified reference design</li> <li>• FCC, ISED and CE</li> </ul>

## Key Applications



## Resources / Getting started

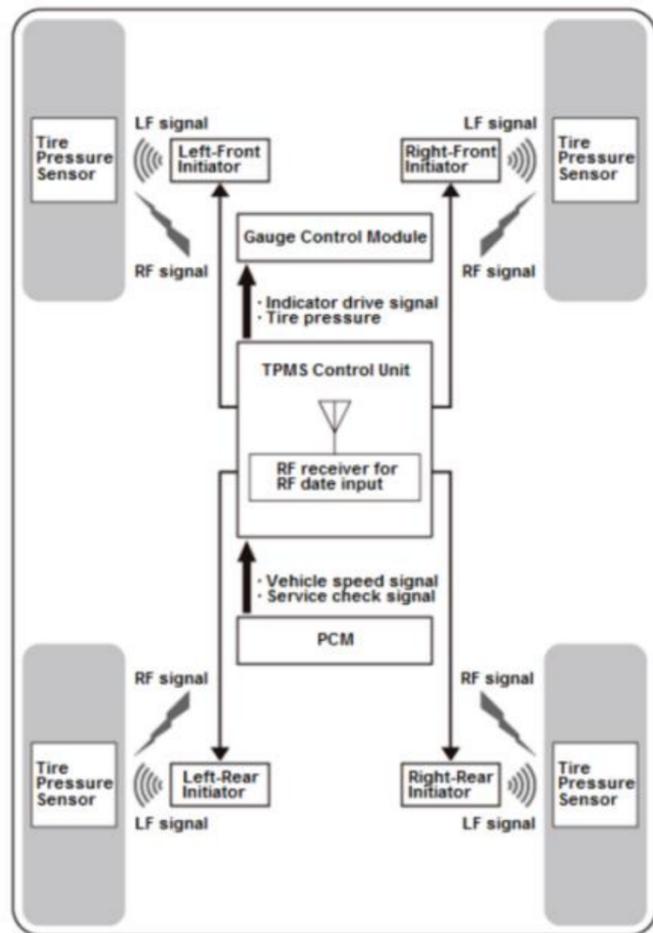
- [CC3135, CC3235x SimpleLink™ Wi-Fi® Internet-on-a Chip™ Solution–BLE Coexistence](#)
- [Low-Power Internet Connectivity Over Wi-Fi \(Rev. A\)](#)

# Agenda

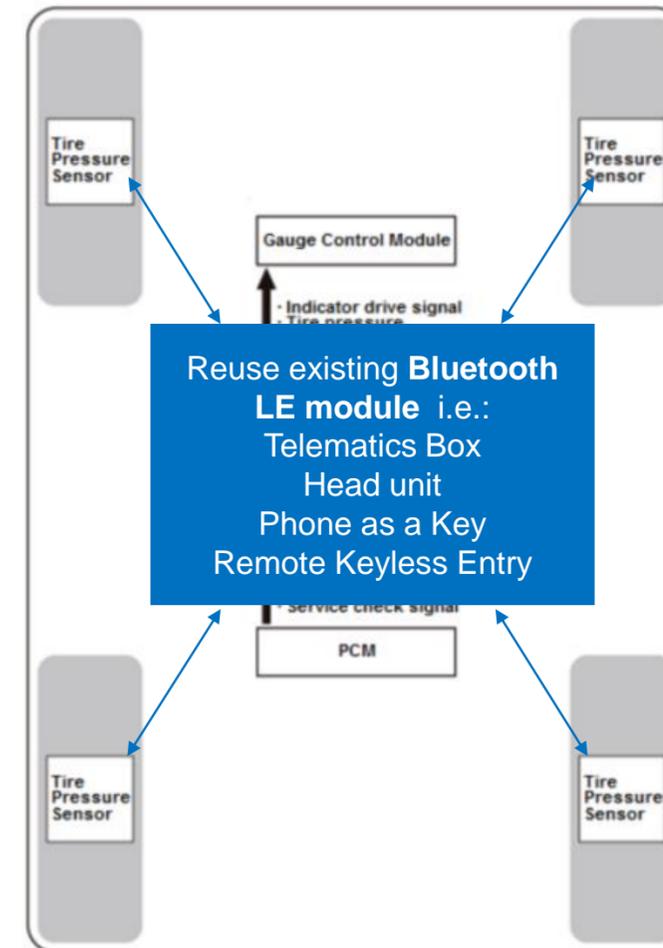
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  - Smart helmet
- Dual-mode Bluetooth

# TPMS | Today and future

## Today



## Future



### System cost saving:

- Re-use of existing vehicle infrastructure
- Weight reduction
- Remove LF system + cables + antennas
- Single solution for all countries (homologation)

### Advanced feature offering:

- TPMS mobile phone apps

### Vehicle

4x LF Transmitter

1x UHF receiver

### 4-8 Sensors

1x LF Wake Receive

1x UHF Transmitter

### Vehicle

4x LF Transmitter

1x UHF receiver



### 4-8 Sensors

1x BLE SoC

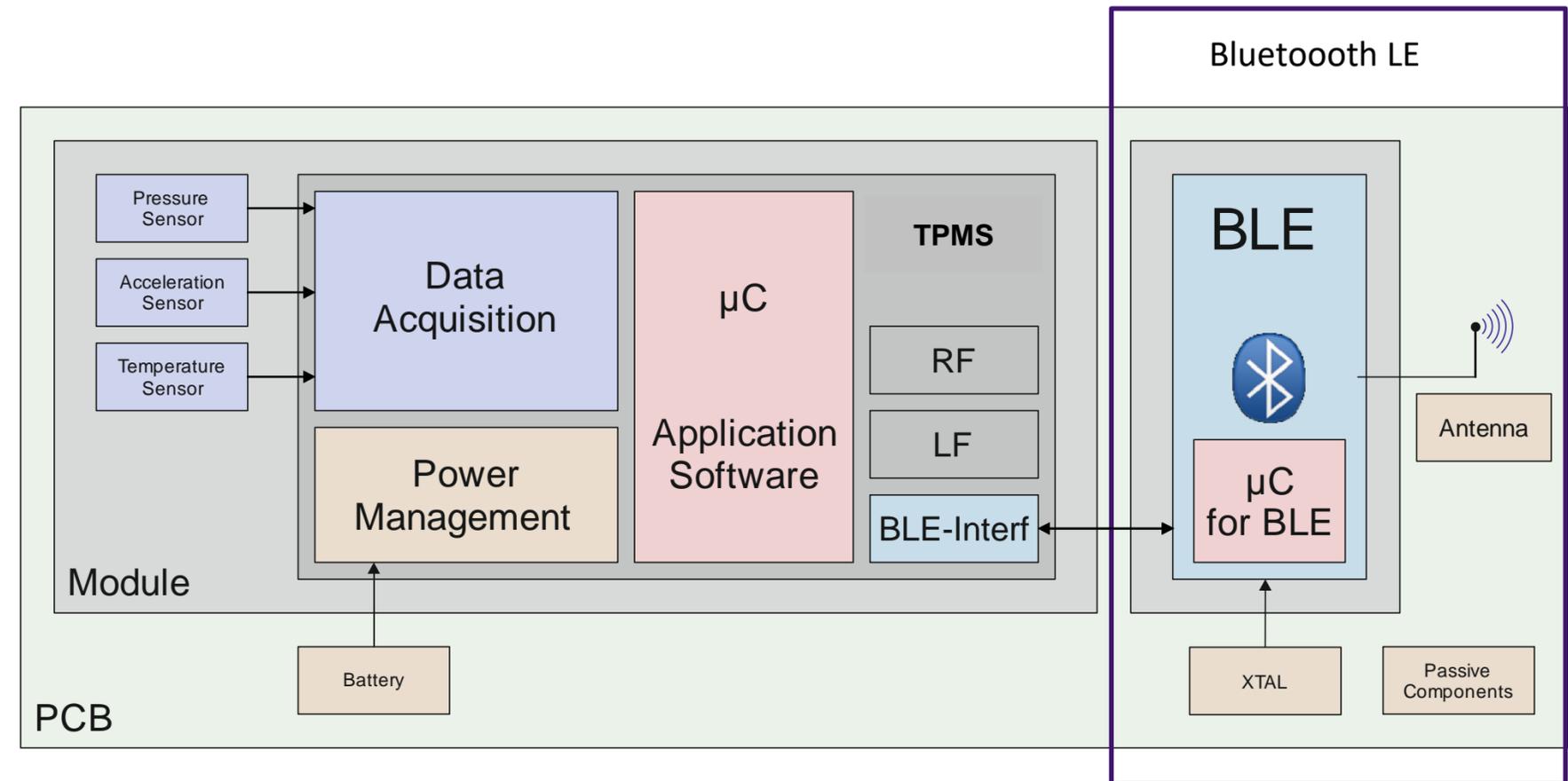
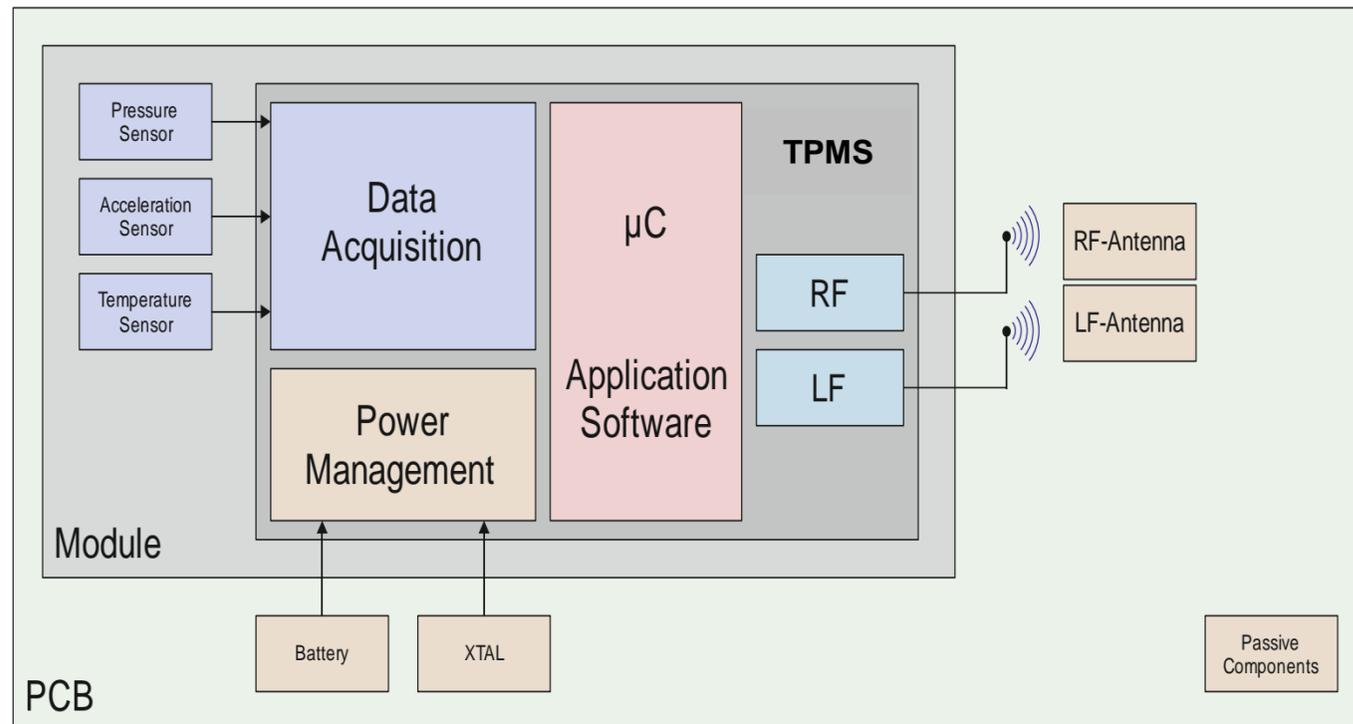
# TPMS | Sensor block diagram



Today

Future

LF/RF



## TI benefits

- Shutdown mode not preferred due to periodic transmissions
- Lowest standby current is most important for battery lifetime
- TI BLE products offer lowest standby current in the market

# Car access | System block diagram

Phone as a key (up to 8)



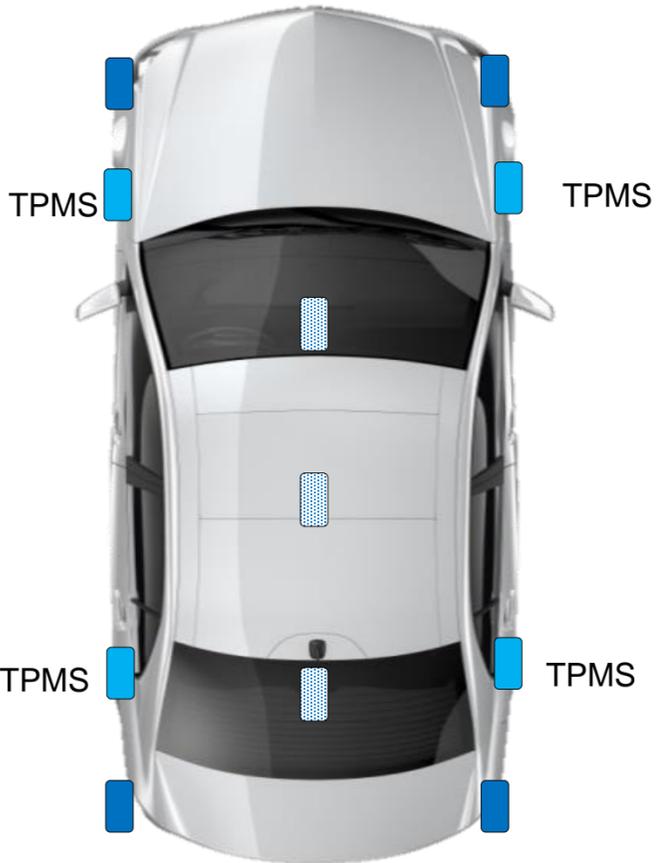
Bluetooth LE Master



Vehicle nodes

- Bluetooth LE peripheral for phones
- Bluetooth LE peripheral or proprietary for key fob
- Bluetooth LE central (SCAN) for TPMS

■ Bluetooth LE nodes  
■ Bluetooth LE TPMS



Key fob (up to 4)



Bluetooth LE central (SCAN) for vehicle



TPMS (4x)



■ Bluetooth LE broadcaster  
■ Bluetooth LE connected

**TI Benefits**

- Software configurable radio enabling newest Bluetooth LE features
- Support up to 32 simultaneous connections
- Proven technology supporting different connection roles (Central, Peripheral, Multirole/Multimode) with multiple OEMs
- Best in class Rx sensitivity
- Ultra-low power
- Continuous quarterly Interoperability testing on flagship phones

# Infotainment | System block diagram

## Phone



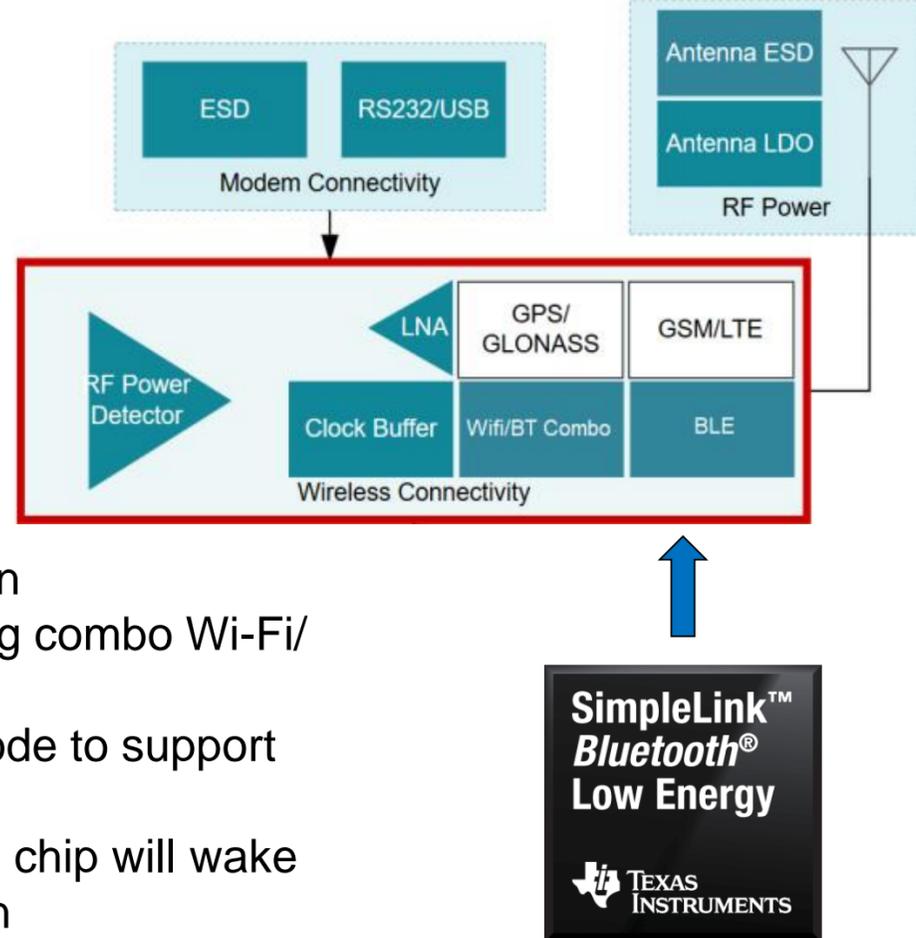
Bluetooth LE master

## Vehicle Nodes

Bluetooth LE peripheral for low power wakeup

## Application

- Head unit/telematics box
- Used as low power auxiliary wireless communication
- When entering ignition-OFF state head unit including combo Wi-Fi/Bluetooth chip will shutdown to save power
- Standalone Bluetooth LE chip enters advertising mode to support low power wakeup
- Once smartphone is back in range the Bluetooth LE chip will wake up the head unit/telematics box for regular operation



## TI benefits

- Software configurable radio enabling newest Bluetooth LE features (BLE 5.x Long Range)
- Ultra low power
- Faster go-to market by easily re-using TI SW/SDK
- Continuous quarterly Interoperability testing on flagship phones.
- Best in class Rx sensitivity
- 1 or 3 wire coexistence

# 2-wheeler cluster | System block diagram

Phone



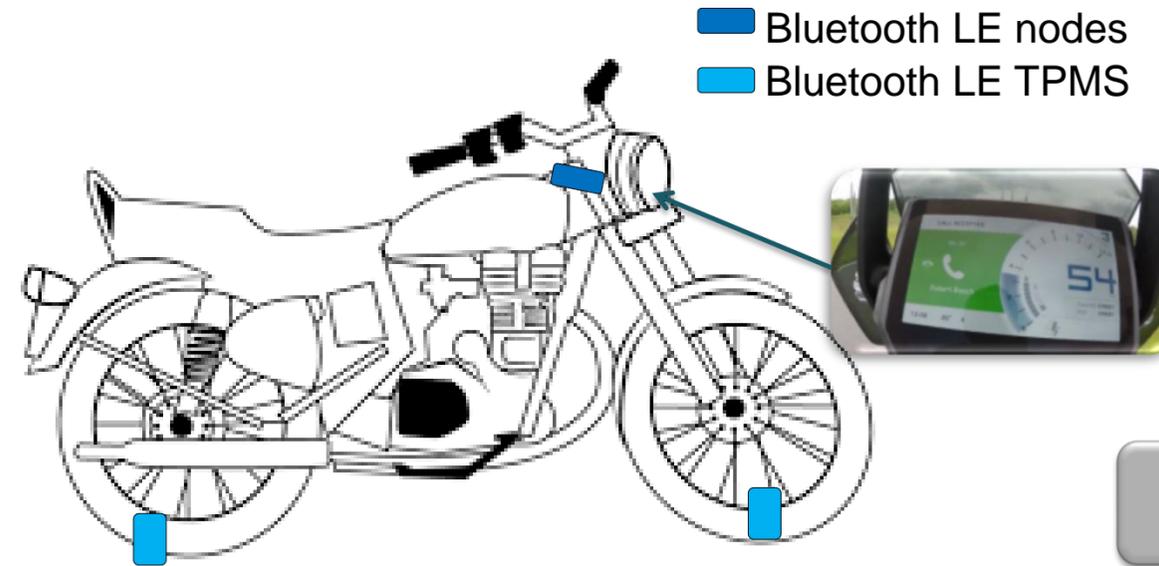
Bluetooth LE master

Vehicle nodes

Bluetooth LE peripheral for phones  
Bluetooth LE central (SCAN) for TPMS

Application

- Connectivity cluster 2-wheeler
- Used as low power auxiliary wireless communication
- Scan/connect to mobile phones
- Indicate incoming calls to helmet
- Mirror GPS/navigation data from phone to cluster
- TPMS signaling to head unit, phone or helmet



SimpleLink™  
Bluetooth®  
Low Energy

TEXAS  
INSTRUMENTS

TPMS (2x)

Bluetooth LE broadcaster  
Bluetooth LE connected

TI benefits

- Software configurable radio enabling newest Bluetooth LE features (BLE 5.x long range)
- Support up to 32 connections for different roles (central, peripheral, multirole/multimode)
- Continuous quarterly Interoperability testing on flagship phones.
- Best in class Rx sensitivity
- Ultra low power
- Faster go-to market by easily re-using TI SW/SDK



# Smart helmet | Dual-mode Bluetooth



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# CC2564C | product highlights



- TI's *Bluetooth*® CC2564C: Dual-mode Bluetooth 5.1 (compliant) controller for legacy and high throughput applications, including integrated audio capabilities
- CC2564C and the TI software stack provide a complete solution, including:
  - LE Secure connections: Bluetooth Low Energy security algorithm (ECDH) for key generation and new pairing procedure for key exchange
  - Link layer topology: Bluetooth Low Energy scatternet capabilities, managing connection in a dual mode topology allowing sensor network topology
  - [QDID 177061](#): Controller subsystem

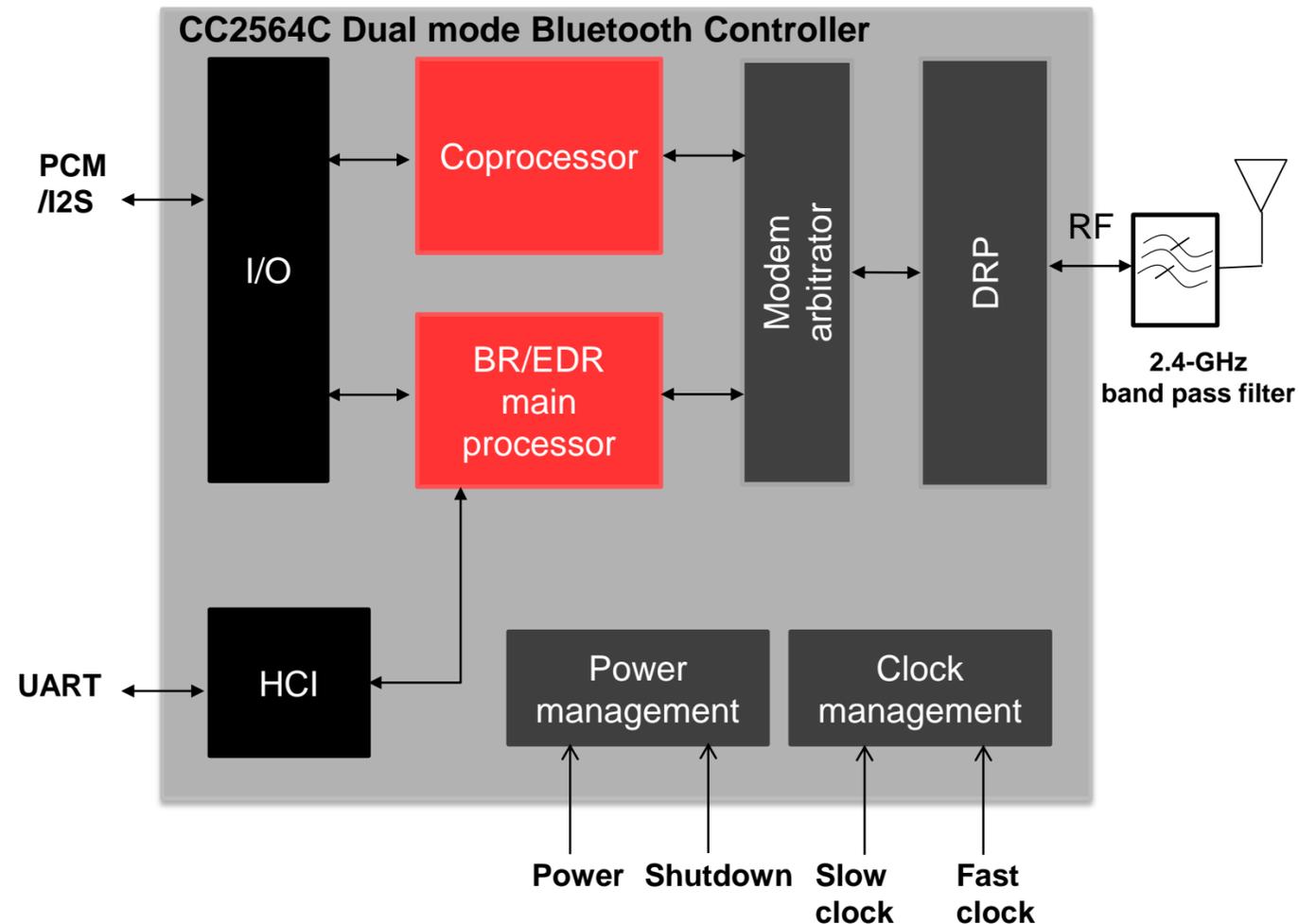
# Dual-mode *Bluetooth*<sup>®</sup> | Hardware

## Key Parameter

- **2.2 - 4.8 V** supply range
- **8 x 8 mm** QFN
- **-40°C to +85°C** temp range
- **UART** host interface
  - 4-wire H4
  - 3-wire H5
- **PCM-I2S** voice/audio I/F
- A2DP internal SBC encoding/decoding is supported
- Bluetooth SIG 5.1 certified
- The evaluation board is FCC, IC and CE certified

## Radio Performance

- **+12 dBm** transmit power (“Class 1.5”)
- **-95 dBm** receive sensitivity



## Target applications

- Wireless audio
- Point of sale (ePOS)
- Medical devices
- Set-top boxes (STBs)
- Wearable devices
- Sensor hub, sensor gateway: home and factory automation
- Industrial: cable replacement
- Automotive aftermarket
- Sports and fitness devices

# Wi-Fi | WL18xx and CC2564C: Controller subsystem qualification

What is it?

**Reclassification** of dual mode Bluetooth transceiver solutions from component to controller subsystem in order to **simplify the certification process for customers**

## Key benefits & features

### Design simplification

- Customers no longer need to register design as controller subsystem based on TI's component
- Ensures longevity of Bluetooth designs (no need to worry about recertification every 3 years)
- No additional RF testing
- No need to address mandatory errata between our qualification and customer certification

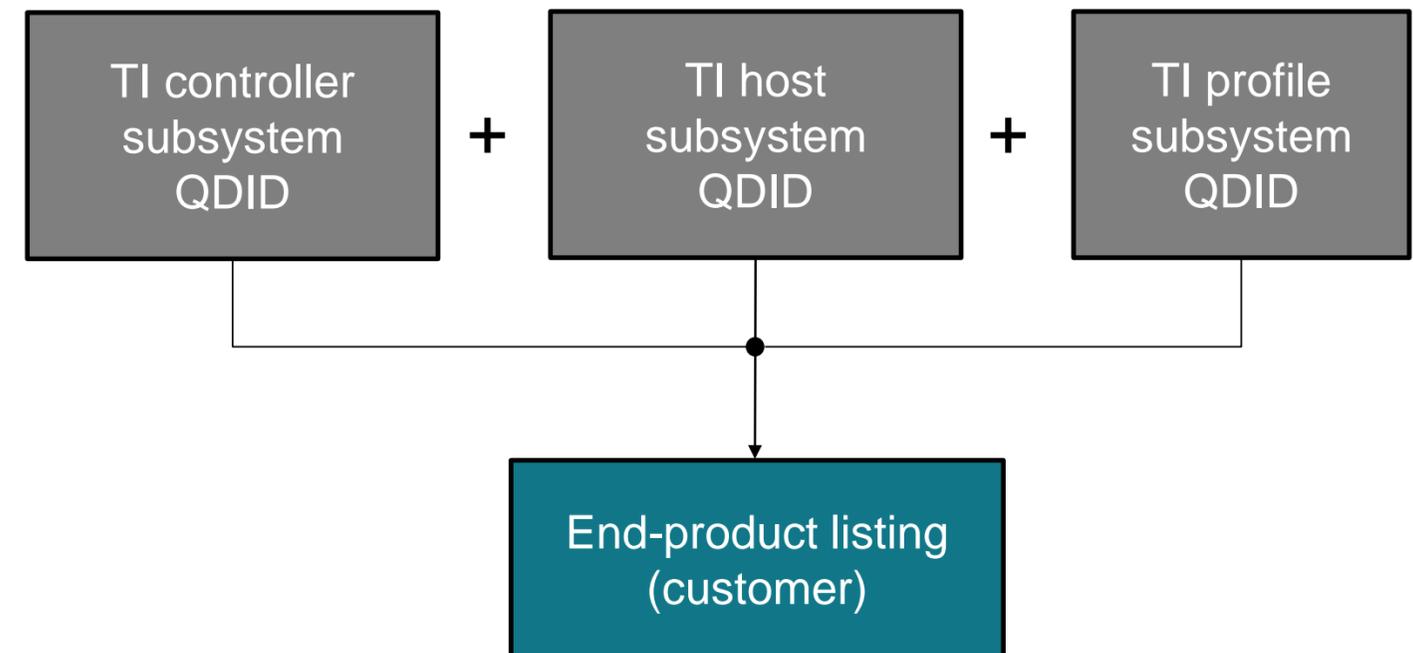
### Recommendations

- Customers must follow TI's guidelines and/or ensure they meet the RF-PHY performance
- Customers should look at the ICS of the certification listing to understand what features are supported
- Product qualification is determined using least common denominator of the Component/Controller Subsystem and Host Subsystem qualifications

## QDID listings:

- [QDID 177062 – WL183x](#)
- [QDID 177061 – CC2564C, BL6450CQ](#)
- [QDID 177060 – WL18xxQ \(v5.0\)](#)

## Bluetooth qualification process:



# Software stack | Overview

## TI's Dual-mode *Bluetooth*<sup>®</sup> stack is based on Bluetopia

The device can be used on any host processor\* with sufficient memory (256KB is the recommended minimum)

Several host platforms are provided and supported directly by TI

MSP432

STM32F4

AM335x

The software stacks are royalty free with TI's CC256x or WiLink<sup>™</sup> 8 devices

Third parties can be contacted for

Custom MCU/MPU porting

Optimization and development

Application integration and custom support

\*Host processor requires software stack compatible with TI's BT controllers

# Software stack

## Bluetooth® software stack

Bluetooth BR/EDR and Bluetooth low energy profiles

- BR/EDR – A2DP, AVRCP, GAP, HSP, HFP, HID, MAP, PBAP, SPP
- Bluetooth LE – ANS, BAS, CSCS, DIS, FMP, GAPS, GATT, HTS, HRS, HIDS, HID over GATT, IAS, LLS, PASS, PXP, TPS

Tool chains supported

- IAR Systems® and Code Composer Studio™ IDE

OS

- No OS, FreeRTOS, Linux

MCU/MPU supported

- MSP432™ microcontrollers
- Sitara™ (Linux)
- STM32 support (No OS/FreeRTOS)

Product info

Selection Guide: [SWRU523](#)  
Product page: <https://www.ti.com/product/CC2564C#software-development>

# Software features

- **LE Secure connections:** Bluetooth Low Energy security algorithm (ECDH) for key generation and new pairing procedure for key exchange
- **Link Layer topology:** Bluetooth Low Energy scatternet capabilities, managing connection in a dual-mode topology allowing sensor network topology
- Enhanced audio time synchronization supporting multi-speaker functionality
- PCM NBS/WBS enhancements
- **IoT:** internet access infrastructure (Bluetooth 4.1 L2CAP dedicated channels)
- Enhanced Voice HFP 1.6 (CSA2 spec commands)
- AFH (adaptive Frequency Hopping) enhancements
- **Security:** Bluetooth Core Errata 10734 and 11838 support

Reusable  
Bluetooth controller (5.1  
compliant) & host stack  
certification

[QDID 177060](#): Controller Subsystem (WL18xxQ)

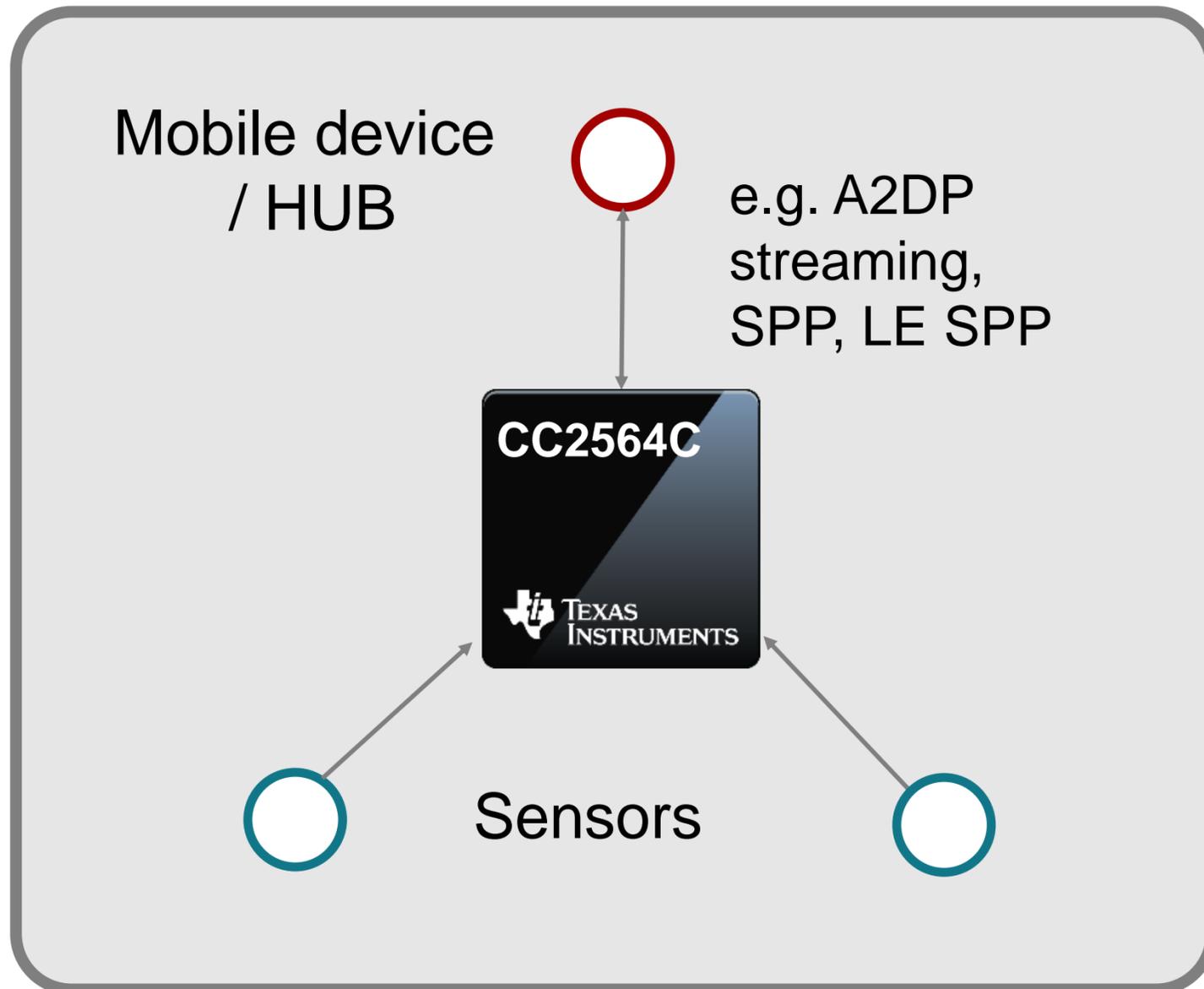
[QDID 177061](#): Controller Subsystem (CC2564C)

[QDID 177062](#): Controller Subsystem (WL183x)

[QDID 172096](#): 5.1 Profile Subsystem

[QDID 172097](#): 5.1 Host Subsystem

# Dual mode/link layer topology



**Dual-mode topology:** Enables a dual-mode device to act as a *Bluetooth*<sup>®</sup> smart ready hub and Bluetooth Low Energy peripheral at the same time. The device can then communicate with Bluetooth Low Energy peripherals on one side and another Bluetooth smart ready hub device on the other side.

**Link layer topology:** Manages the connections between the devices used in a dual-mode topology implementation.

Source: Bluetooth SIG

# Pick the right part – Key Bluetooth/Bluetooth LE dual mode options

Part number 	Typical use case 	BT HCI spec supported (controller certification)	TI Bluetooth Stack spec supported (host subsystem)	BT profile support	OS	Automotive Temp	Certified TI module available	Optional BLE features supported
<b><u>CC2564MODA</u></b> (Based on <b><u>CC2564B</u></b> )	Headsets, hubs, point-of-sale systems BT Audio and legacy profile applications. Dual mode BT classic (BR/EDR) + BLE	<b><u>4.1</u></b>	<b><u>4.2</u></b>	See <b><u>QDID172096</u></b> , <b><u>QDID69886</u></b>	RTOS Linux		yes	
<b><u>CC2564C</u></b>	Best for headsets, hubs, point-of-sale systems that require BT classic + BLE Best for future-proofing - BT SIG certification	<b><u>5.1</u></b>	<b><u>4.2</u></b> 5.1 coming 4Q21		RTOS Linux			
<b>BL6450CQ</b>	Automotive dual-mode BT infotainment applications, such as head units	<b><u>5.1</u></b>	<b><u>4.2</u></b> 5.1 coming 4Q21		RTOS Linux	yes		
<b><u>WL1831MOD</u></b> (part of the <b><u>Wi-Fi family</u></b> )	Wi-Fi + BT/BLE on one chip Seamless Wi-Fi and BT/BLE coexistence.	<b><u>5.1</u></b>	<b><u>4.2</u></b> 5.1 coming 4Q21		Linux		yes	
<b><u>CC2642R</u></b> (part of the <b><u>2.4GHz family</u></b> )	BLE only Peripherals, central roles BLE mesh, Long range and high bandwidth	<b><u>5.2</u></b>	5.2	No BT classic support	RTOS			LE coded PHYs (Long Range)  LE 2-Mbit PHY (High speed)

**Thank you!**



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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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